

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L1 | 961 | (361/707).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/03/07 09:21 |
| L2 | 814 | L1 and @pd< "20031205" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/07 12:53 |
| L3 | 69 | I2 and (plasma or LCD or LED) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/07 09:50 |
| L4 | 15 | I2 and plasma | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/07 09:51 |
| L5 | 5 | ("5971566" "5990618" "6198222").PN. OR ("6373702").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/03/07 10:25 |
| L6 | 5626 | (plasma with display) and (substrate or circuit\$1board) and heat | US-PGPUB; USPAT; USOCR | OR | ON | 2006/03/07 10:26 |
| L7 | 4378 | (plasma adj display) and (substrate or circuit\$1board) and heat | US-PGPUB; USPAT; USOCR | OR | ON | 2006/03/07 10:27 |
| L8 | 2500 | (plasma adj display) and (substrate or circuit\$1board) and heat and plate and metal | US-PGPUB; USPAT; USOCR | OR | ON | 2006/03/07 10:27 |
| L9 | 791 | (plasma adj display) and (substrate or circuit\$1board) and heat and plate and metal and ((electronic adj circuit) or chip or (electronic adj device)) | US-PGPUB; USPAT; USOCR | OR | ON | 2006/03/07 10:28 |
| L10 | 343 | L9 and @pd< "20031205" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/07 12:38 |

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| L11 | 2156 | L7 and @pd< "20031205" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/07 12:38 |
| L12 | 26 | L11 and (copper with thermal) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/07 12:52 |
| L13 | 0 | (thermal adj interface adj (material or film)) with (spring or compliant or stiffness) with (copper) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/07 12:53 |
| L14 | 64 | (thermal adj interface adj (material or film)) with (spring or compliant or stiffness) and (copper) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/07 12:53 |
| L15 | 25 | L14 and @pd< "20031205" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/07 12:54 |
| S1 | 942 | (361/707).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/03/07 09:21 |
| S2 | 381241 | (circuit or mother) adj board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/29 12:41 |
| S4 | 5 | S1 and S3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/29 12:42 |

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| S5 | 581 | S1 and S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/29 12:45 |
| S6 | 331 | S5 and cool\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/29 12:46 |
| S7 | 4450 | plasma and ((electronic adj device) or (electronic adj circuit) or (electronic adj chip) or (electronic adj component) or ((mother\$1board or circuit\$1board) adj component)) and cool\$3 and (enclosure or frame or chassis or cover) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/29 14:41 |
| S8 | 1734 | S7 and (circuit or mother) and board | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/29 14:41 |
| S9 | 673 | S7 and ((heat adj sink) or (thermal adj plate)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/29 14:42 |
| S10 | 2 | ("5268815").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/03 09:32 |
| S11 | 4 | ((("6233150") or ("6188567"))).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/03 10:30 |
| S12 | 0 | ("200500778446").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/03 10:31 |

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| S13 | 2 | ("0778446").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/03 10:31 |
| S14 | 1 | 10/953340 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/03 10:41 |
| S15 | 125 | (heat adj sink) and (retention adj module) and ((mother or circuit) adj board) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/03 10:43 |
| S16 | 25895 | intel .as. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/03 10:43 |
| S17 | 15 | S15 and S16 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/03 10:43 |
| S18 | 21 | (heat adj sink) and (retention adj module) and S16 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/03 11:28 |
| S19 | 2 | ("5268815").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/03 12:27 |
| S20 | 1292 | (361/687).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/10/03 12:27 |

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| S21 | 18 | (plasma) and S20 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/03 12:27 |
| S22 | 0 | (10/953340).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/03/01 10:51 |
| S23 | 1 | 10/953340 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 10:57 |
| S24 | 960 | (361/707).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/03/01 12:38 |
| S25 | 1370 | (361/687).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/03/01 15:20 |
| S26 | 2 | (plasme adj display) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 12:40 |
| S27 | 51962 | (plasma adj display) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 12:40 |
| S28 | 4836 | plasma and ((electronic adj device) or (electronic adj circuit) or (electronic adj chip) or (electronic adj component) or ((mother\$1board or circuit\$1board) adj component)) and cool\$3 and (enclosure or frame or chassis or cover) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 12:48 |

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| S30 | 41266 | (plasma with (device or display or monitor)) .ti. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 12:44 |
| S31 | 20 | S30 and S28 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 12:50 |
| S32 | 4836 | plasma and ((electronic adj device) or (electronic adj circuit) or (electronic adj chip) or (electronic adj component)) and cool\$3 and (enclosure or frame or chassis or cover) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 12:50 |
| S33 | 8313 | plasma and ((electronic adj device) or (electronic adj circuit) or (electronic adj chip) or (electronic adj component)) and cool\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 12:50 |
| S34 | 46 | S30 and S33 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 12:50 |
| S35 | 26 | S34 not S31 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 12:50 |
| S36 | 931 | S25 and @pd< "20031205" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 15:21 |
| S37 | 961 | (361/707).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/03/02 14:50 |

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| S38 | 814 | S37 and @pd< "20031205" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 16:32 |
| S39 | 14300 | (multi\$1chip adj module) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:17 |
| S40 | 41 | (mother\$1board with chassis with attach\$4) and (fastener or screw or stand\$1off) and heat | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:10 |
| S41 | 143 | (mother\$1board with chassis with attach\$4) and (fastener or screw or stand\$1off) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:11 |
| S42 | 145 | S41 notl4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:11 |
| S43 | 102 | S41 not S40 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:14 |
| S44 | 40 | S43 and @pd< "20020111" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:27 |
| S45 | 7628 | S39 and package | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:18 |

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| S46 | 5076 | S45 and @pd< "20031205" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:18 |
| S47 | 1715 | ((mother\$1board or circuit\$1board or substrate or package) and (heat or thermal) with (conduct\$3) with (post or stud or terminal or jumper) and solder) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:26 |
| S48 | 836 | S47 and @pd< "20020111" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/02 15:27 |
| S49 | 2 | ("5548090").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/03/02 16:32 |
| S50 | 2 | 10/792231 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/06 12:59 |